FORCE DISTRIBUTING SPRING ELEMENT

Abstract

A force distributor is configured for disposition between a printed circuit board and a stiffening plate, which is spaced from the printed circuit board. The force distributor is configured to distribute a compressive force between the printed circuit board, an interposer and a land grid array module carried on a side of the printed circuit board opposite the stiffening plate. The force distributor comprises a spring element comprising a first portion and a second portion with the first portion extending radially outward from the second portion. The spring element is configured for placement so that the first portion is secured to the stiffening plate and the second portion is biased in unsecured, pressing contact against the printed circuit board.

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